

## SEMICONDUCTOR PACKAGE INCLUDING STACKED CHIPS

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### ABSTRACT OF THE DISCLOSURE

10 Semiconductor packages are disclosed. An exemplary  
package includes horizontal leads each having a first side  
and an opposite second side. The second side includes a  
recessed horizontal surface. Two stacked semiconductor  
chips are within the package and are electrically  
interconnected in a flip chip style. One chip extends over  
the first side of the leads and is electrically connected  
15 thereto. The chips are encapsulated in a package body  
formed of an encapsulating material. The recessed  
horizontal surface of the leads is covered by the  
encapsulating material, and a portion of the second side of  
each lead is exposed at an exterior surface of the package  
20 body as an input/output terminal. A surface of one or both  
chips may be exposed. The stack of chips may be supported  
on the first side of the leads or on a chip mounting plate.